

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 09/652,534  
Priority Filing Date .... August 31, 2000  
Inventor .... Sujit Sharan et al.  
Assignee .... Micron Technology, Inc.  
Priority Group Art Unit .... 2823  
Priority Examiner .... Trung Q. Dang  
Attorney's Docket No. .... MI22-2360  
TITLE: Plasma Enhanced Chemical Vapor Deposition Methods and Semiconductor  
Processing Methods of Forming Layers and Shallow Trench Isolation Regions

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Assistant Commissioner for Patents  
Washington, D. C. 20231  
Attention: Official Draftsman


**SUBSTITUTE DRAWING REQUEST**

Please enter the enclosed substitute drawings in the above-referenced application in place of drawings originally filed. The content of the drawings are identical to those now on file in this application.

Acknowledgment of receipt of the formal drawings and their acceptance into the file is requested.

Respectfully submitted,

Date: 7-16-03

By:   
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Enclosures:            Sheets of Formal Drawings, Figs. 1-6.